



Charge carrier detrapping in irradiated silicon sensors after microsecond laser pulses

Markus Gabrysch¹, Mara Bruzzi², Riccardo Mori²,
Michael Moll¹, Hannes Neugebauer¹,
Marcos Fernández Garcia³

¹ PH-DT-DD, CERN (CH)

² INFN and University of Florence (IT)

³ IFCA-Universidad de Cantabria (ES)

Outline

1. Motivation/Aim
2. Setup and diodes
3. Photocurrent during illumination
4. TCAD simulations
5. Measurements and method
6. Conclusions

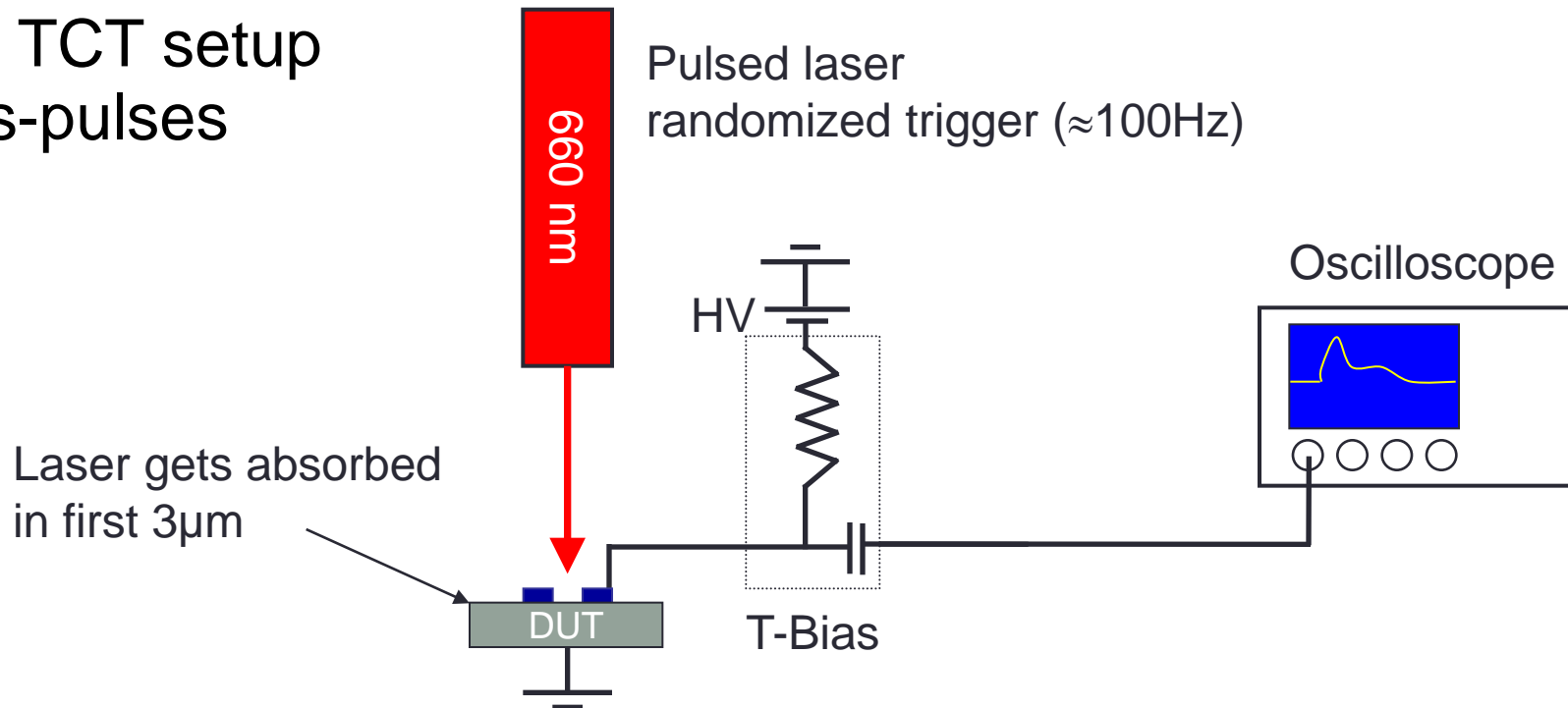
Motivation/Aim

- Knowledge of energy levels and cross-sections of de-trapping centres is crucial for defect characterization
- These parameters can be determined by investigating the temperature dependence of the time-constant τ for de-trapping
- For defects deep in the bandgap the de-trapping happens on a μs -timescale (around RT)

- Previous work: see e.g. Kramberger, Cindro, Mandic, Mikuz, Zavrtnika, “Determination of detrapping times in semiconductor detectors” (2012 JINST 7 P04006)

Setup and Diodes

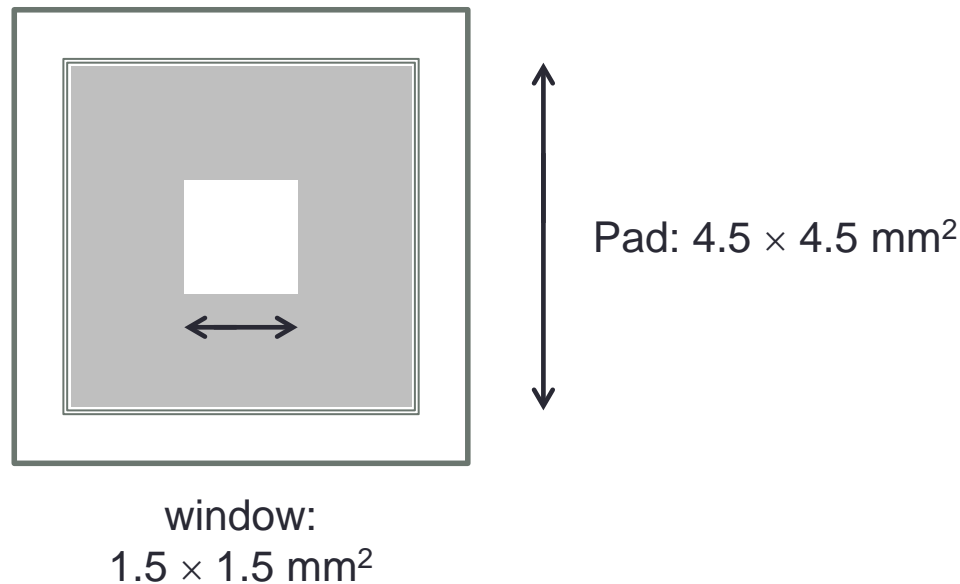
CERN TCT setup for μs -pulses



- Red laser illumination with variable pulse width ($0.5 - 20\mu\text{s}$)
- Variable bias voltage with T-Bias ($20\text{kHz}-10\text{GHz}$, $\text{HV} < 200\text{V}$)
- Amplifier was not used (to have maximal bandwidth, but: $\sim 1\text{mV}$ signals)
- Temperature controlled (flushed with dry air for $T < 10^\circ\text{C}$)

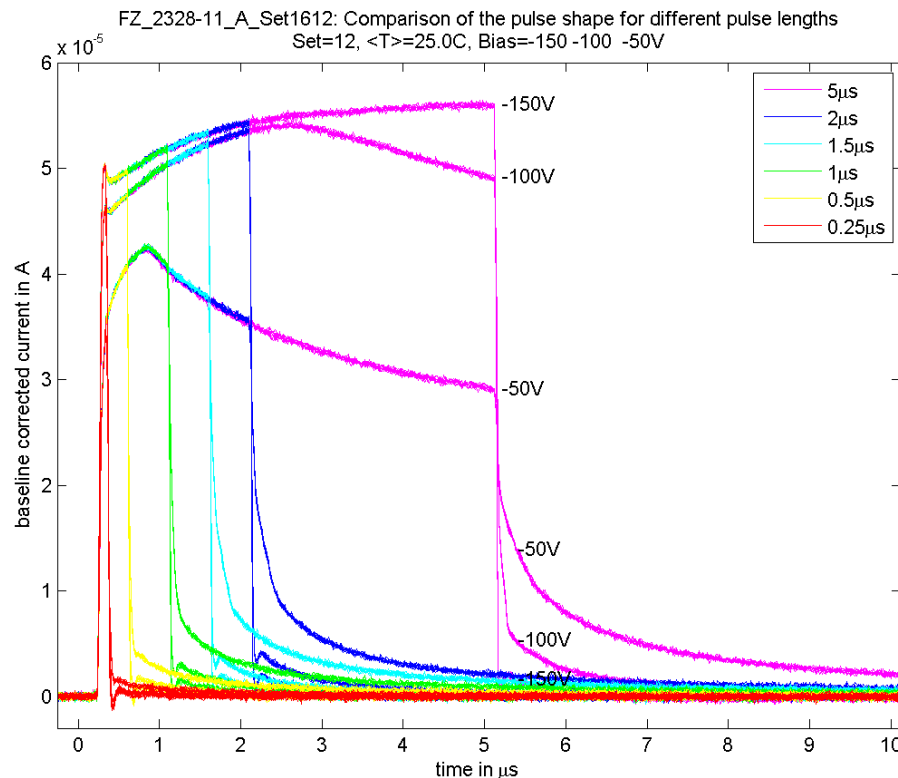
Investigated diodes

- Material: Micron, 300 μm , FZ p- and n-type
- Irradiation: 24GeV protons with $\Phi = 5 \times 10^{14}$, 1×10^{14} , 5×10^{13} , 1×10^{13} p/cm⁻²
- Annealing: 80min at 60°C
- Illumination: front (back fully metalized)



Example of transient current

- TCT signals have been measured (up to 50 μ s after illumination)
- Temperature range investigated: ca. -10 to 30 $^{\circ}$ C
- Stability of signal confirmed by recording 10 times the (same) waveform which itself is an average of 1024 shots



Example:

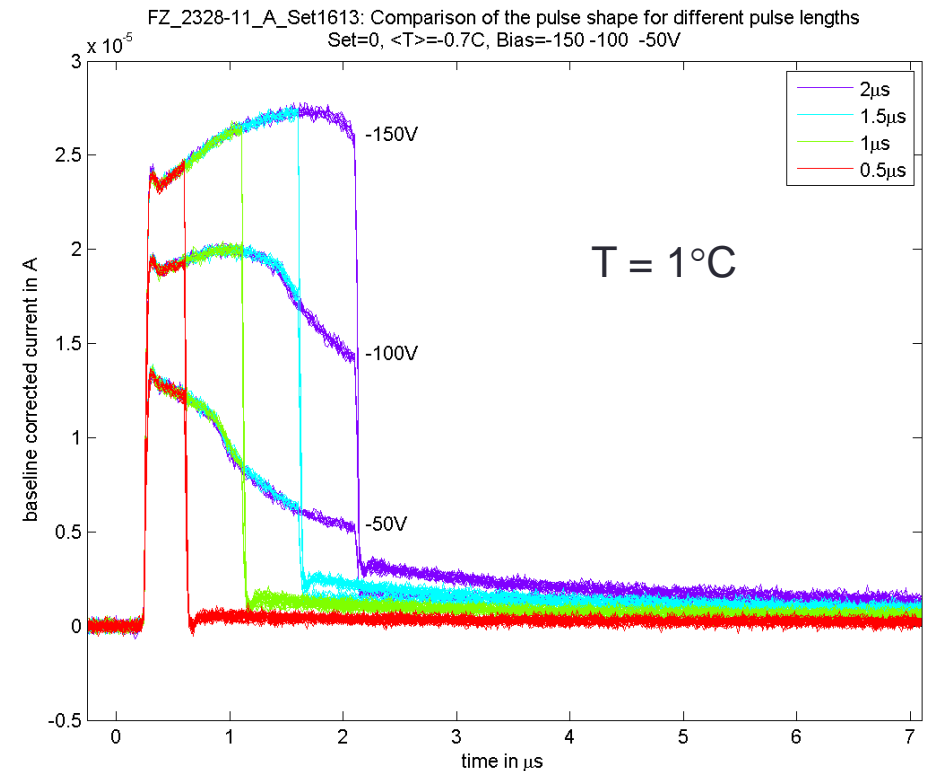
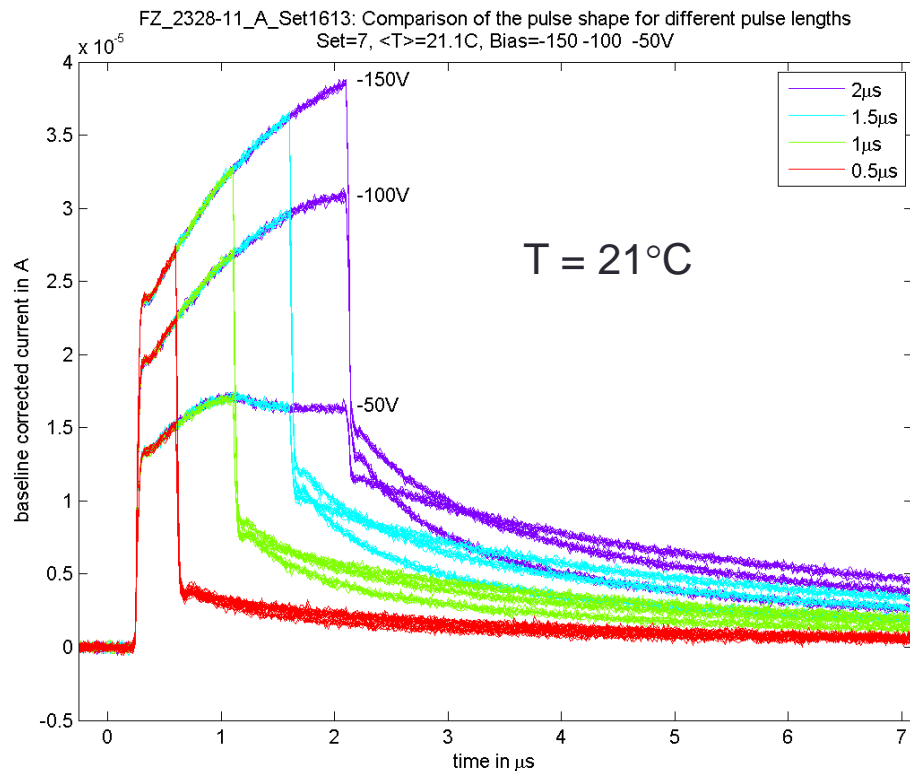
- 1e14p/cm²
- n-in-p (holes transport)
- T = 21 $^{\circ}$ C
- Bias: 50, 100, 150V
- Pulse length: 0.25-5 μ s
- 660nm, top illumination

Photocurrent during illumination

Photocurrent during illumination

- Current can drop during illumination
- Happens mostly for lower bias voltage and lower temperature

Example: $5e14p/cm^2$, n-in-p (holes transport)



Photocurrent during illumination

- Current can drop during illumination
- Happens mostly for lower bias voltage and lower temperature
- This effect is also visible in TCAD simulations and can be explained by a reduction of the active volume due to trapped charges

TCAD Simulations (Synopsis)

Synopsis TCAD Simulation of TCT signal of irradiated diode

Device

- silicon: p-type; $5e11\text{cm}^{-3}$ boron ($V_{\text{dep}}(300\mu\text{m})=35\text{V}$; $25\text{k}\Omega\text{cm}$)
- bulk dimensions: $300\times 10\times 1\ \mu\text{m}^3$ (x-y-z)
- diode: n-p-p
- 1 defect: D01 – CiOi (donor): $E = 0.36\text{eV}$, $\sigma_e = 2.1e-18\ \text{cm}^2$, $\sigma_h = 2.5e-15\ \text{cm}^2$
generation rate : $g = 0.7\ \text{cm}^{-1}$ (24GeV/c protons) such that $N_{\text{defect}} = g \times \Phi$

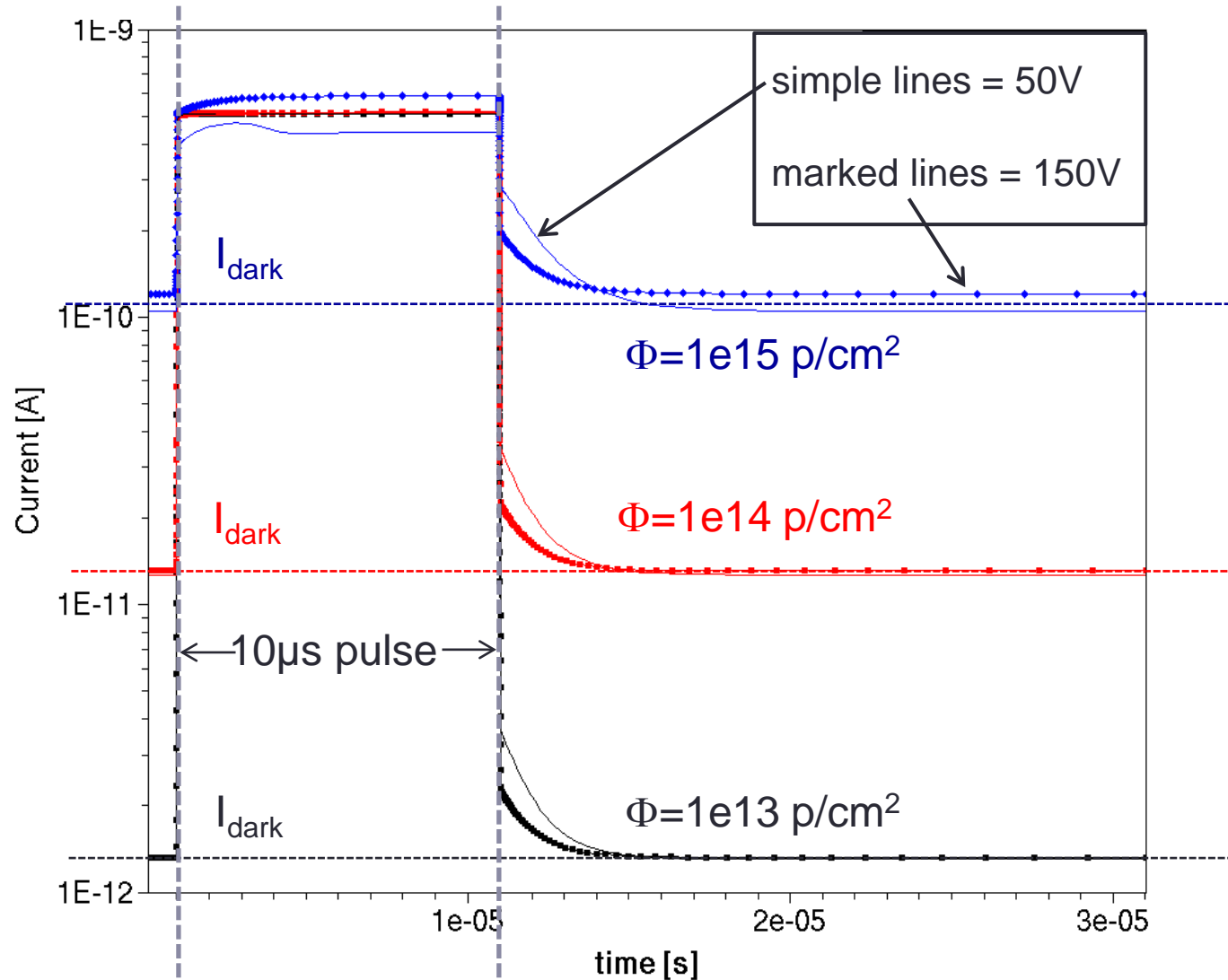
Light pulse

- 660 nm, $10\text{mW}/\text{cm}^2$
- linear rise and linear fall in intensity from 0 to 100% in 1ns
- pulse length (variable, μs -order)

Physics

- Simulation: Synopsys TCAD F-2011.09
- Temperature: 300K
- Leakage current via SRH lifetime “generated” (more details in M.Moll’s talk tomorrow)

Synopsis TCAD Simulation of TCT signal of irradiated diodes



**All data for
300K**

Note:

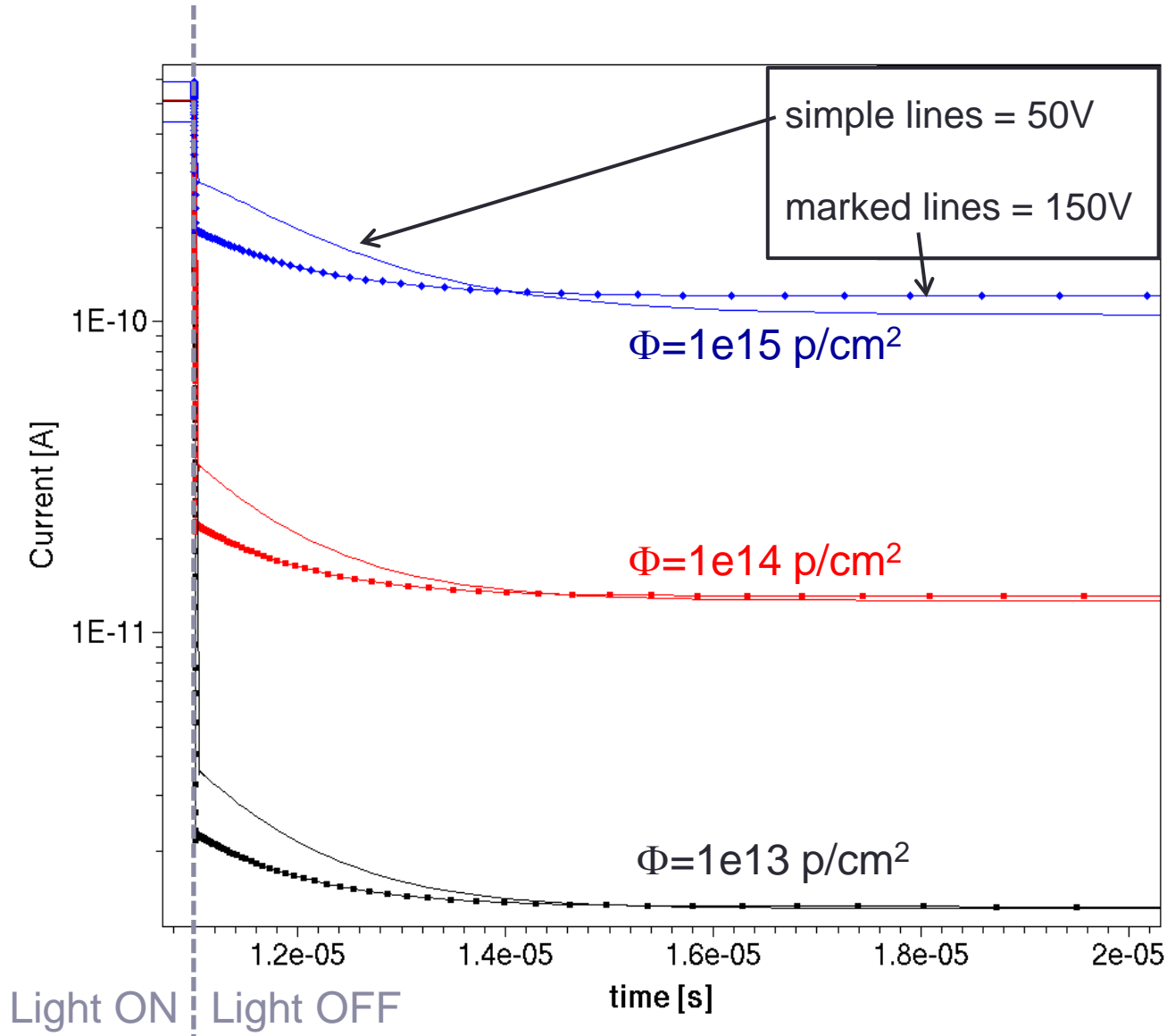
- All currents for the simulated volume of $300 \times 10 \times 1 \mu\text{m}^3$
- In experiment we have diodes with $300 \times 5000 \times 5000 \mu\text{m}^3$
- we need a scaling factor of $\approx 2.5e6$ such that, e.g., I_{dark} for $1e14 \text{ p/cm}^2$ is $\approx 30\mu\text{A}$ (but in exp.: $\approx 100\mu\text{A}$)

Light OFF

Light ON

Light OFF

Why do we have higher transients for lower bias voltage?

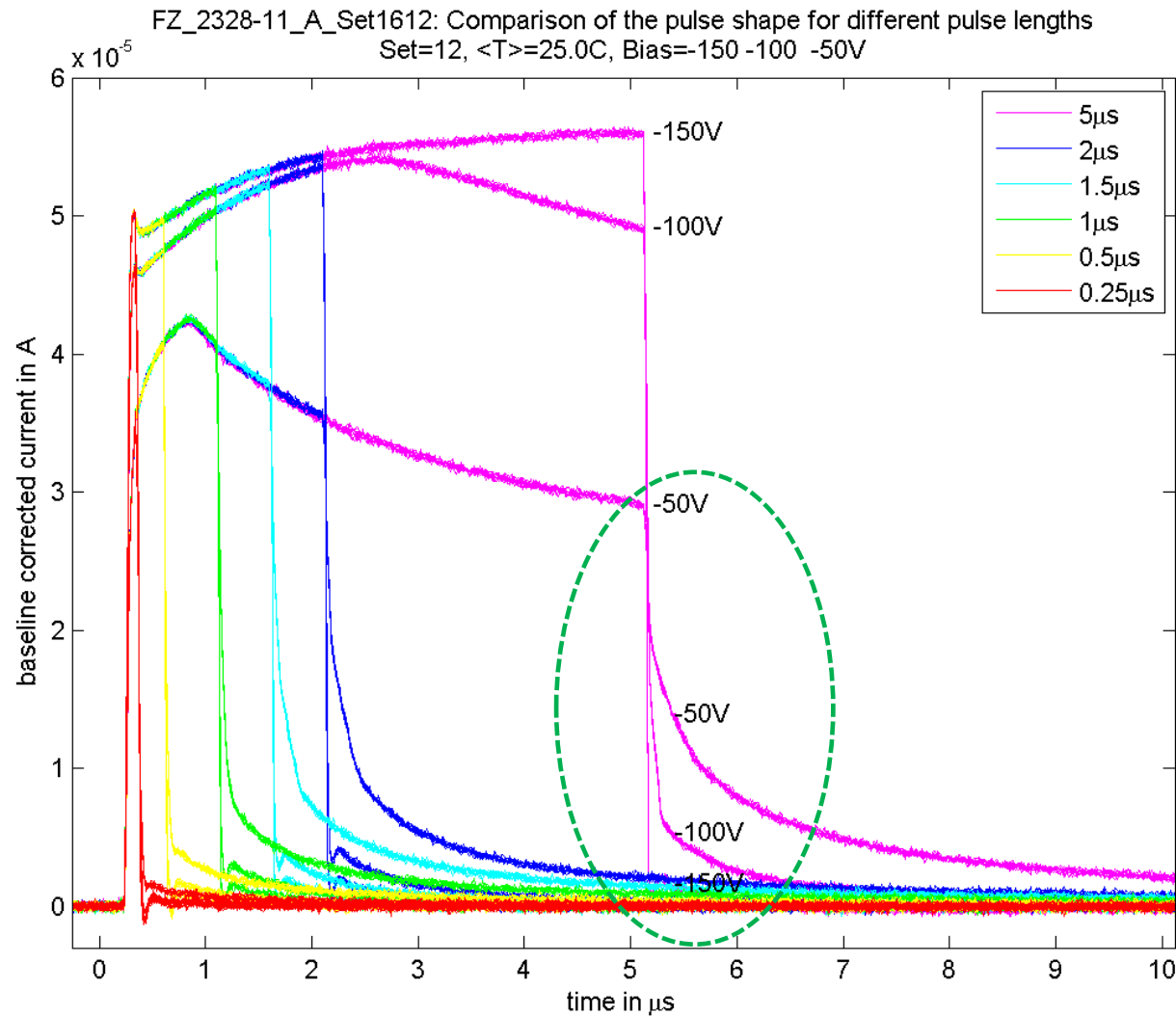


**Light OFF
transient**

Observations:

- High transient amplitude after light pulse for lower voltage
- We have a better trap filling for lower voltage
- This can be seen in the defect occupancy plot on next slide

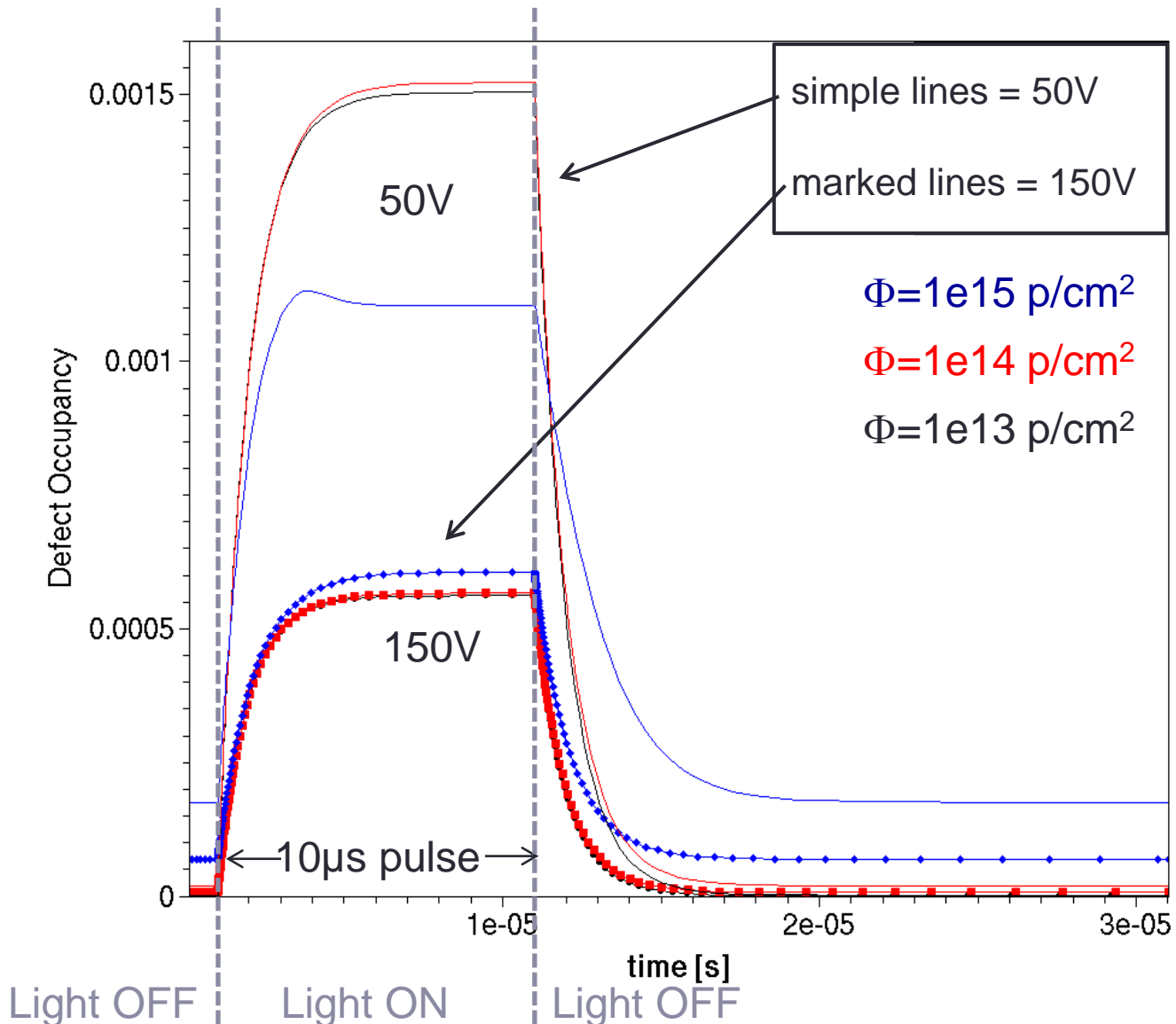
Example from slide 7



Example:

- $1\text{e}14\text{p}/\text{cm}^2$
- n-in-p (holes transport)
- $T = 21^\circ\text{C}$
- Bias: 50, 100, 150V
- Pulse length: 0.25-5 μs
- 660nm, top illumination

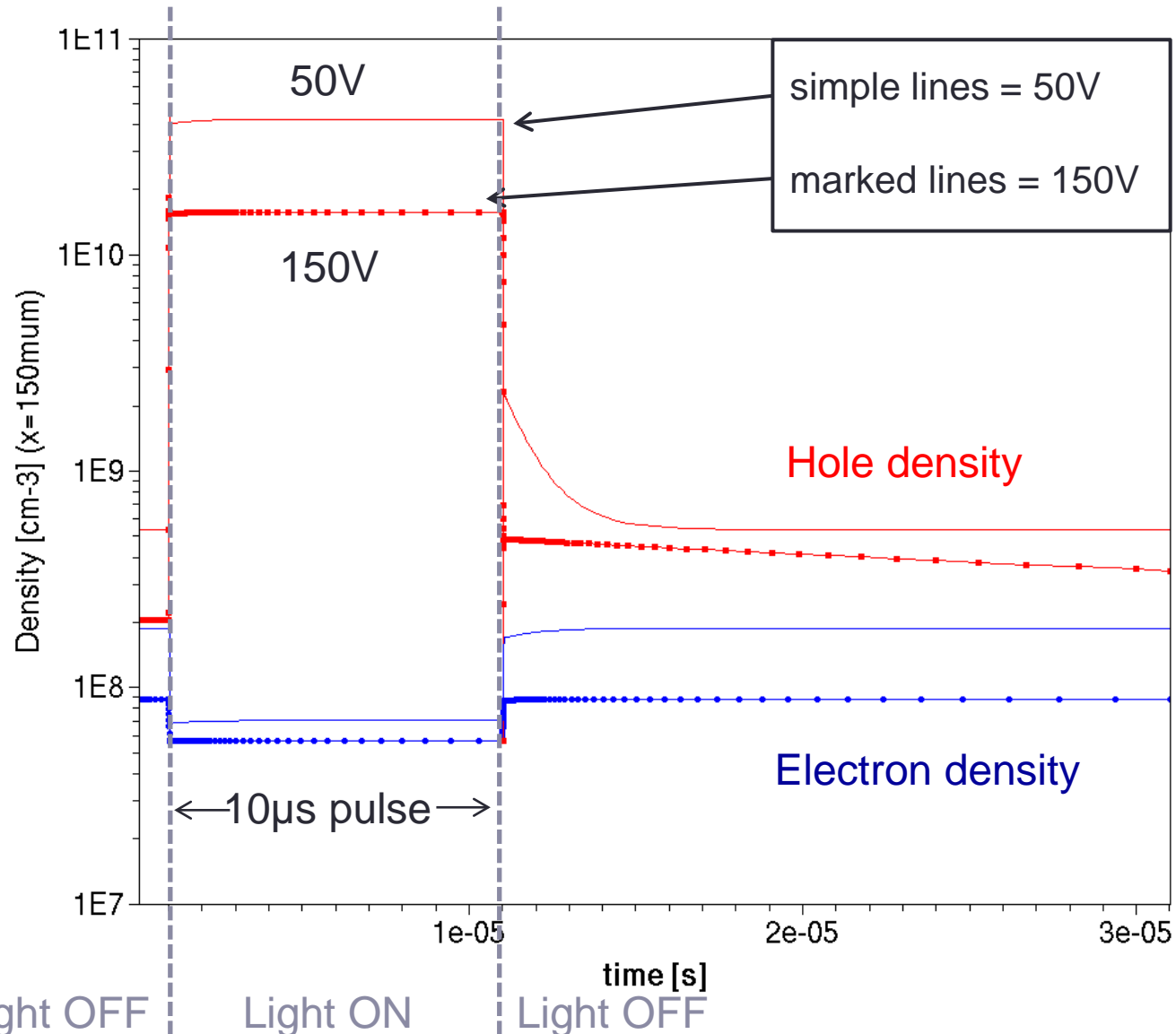
Defect Occupancy at $x=150\mu\text{m}$



Observations:

- Higher defect occupancy for lower voltage
- This is a result of higher hole density for lower voltage

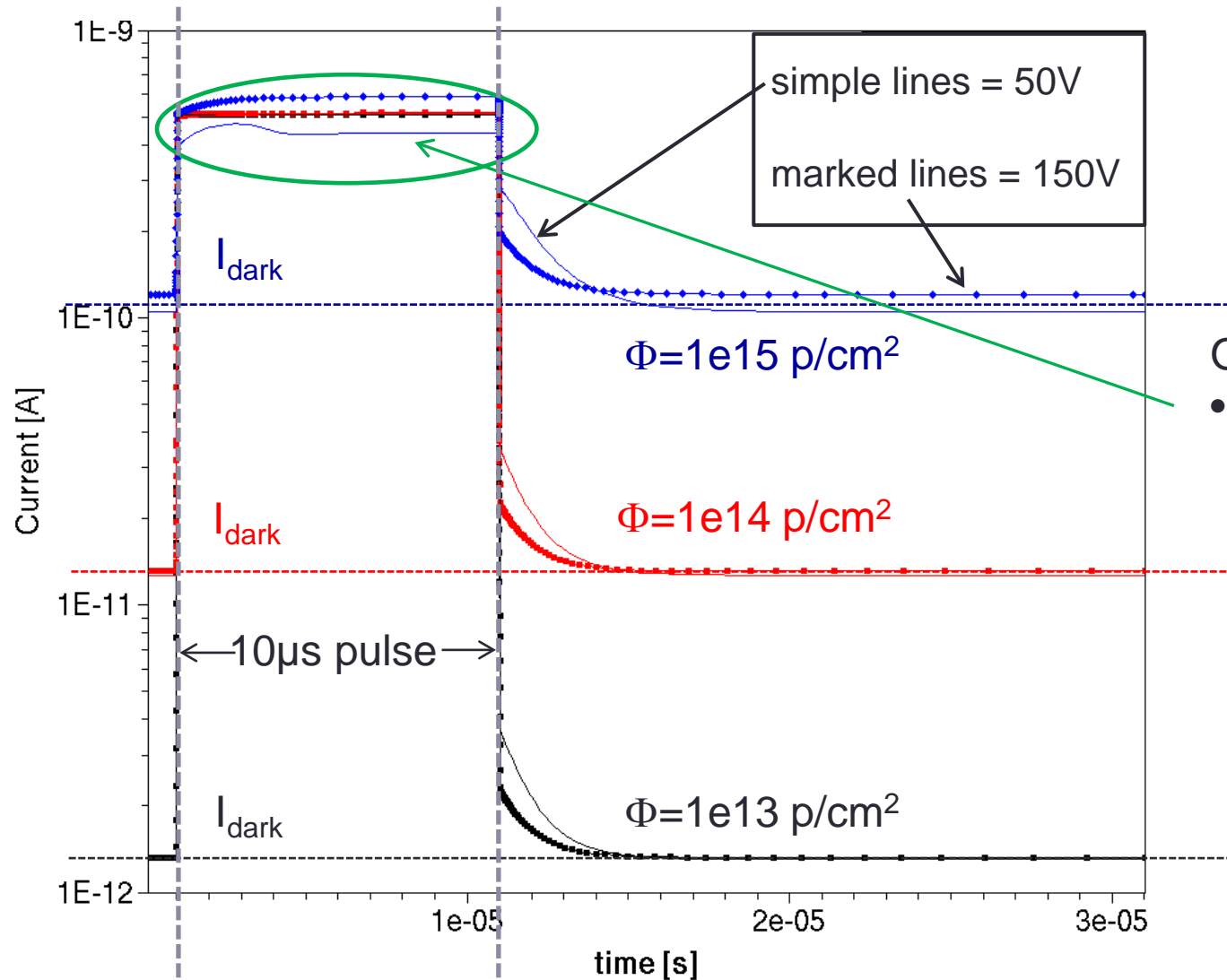
Electron and Hole Densities at $x=150\mu\text{m}$ for $\Phi=1\text{e}14\text{ p/cm}^2$



Explanation:

- Higher hole density for lower voltage
→ higher occupancy
→ larger transient
- Note: the transient currents for 50 and 100V in the case of $1\text{e}14\text{ p/cm}^2$ were the same. Since v_{drift} is lower for 50V we need higher carrier density to obtain the same current.

Why do we see a current drop for high fluence and low bias?



Observations:

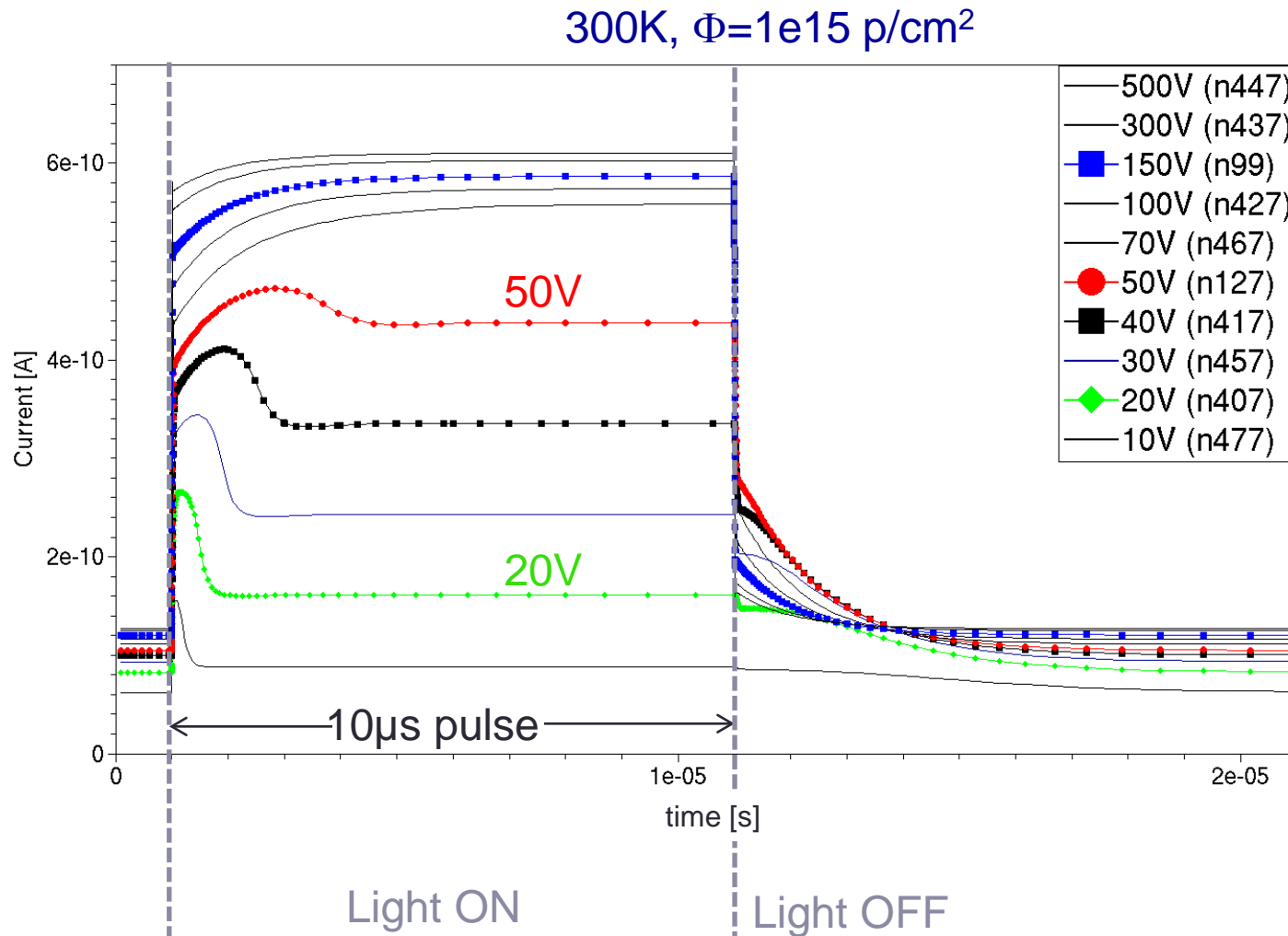
- Current drops during illumination for 50V and $\Phi = 1e15 \text{ p/cm}^2$

Light OFF

Light ON

Light OFF

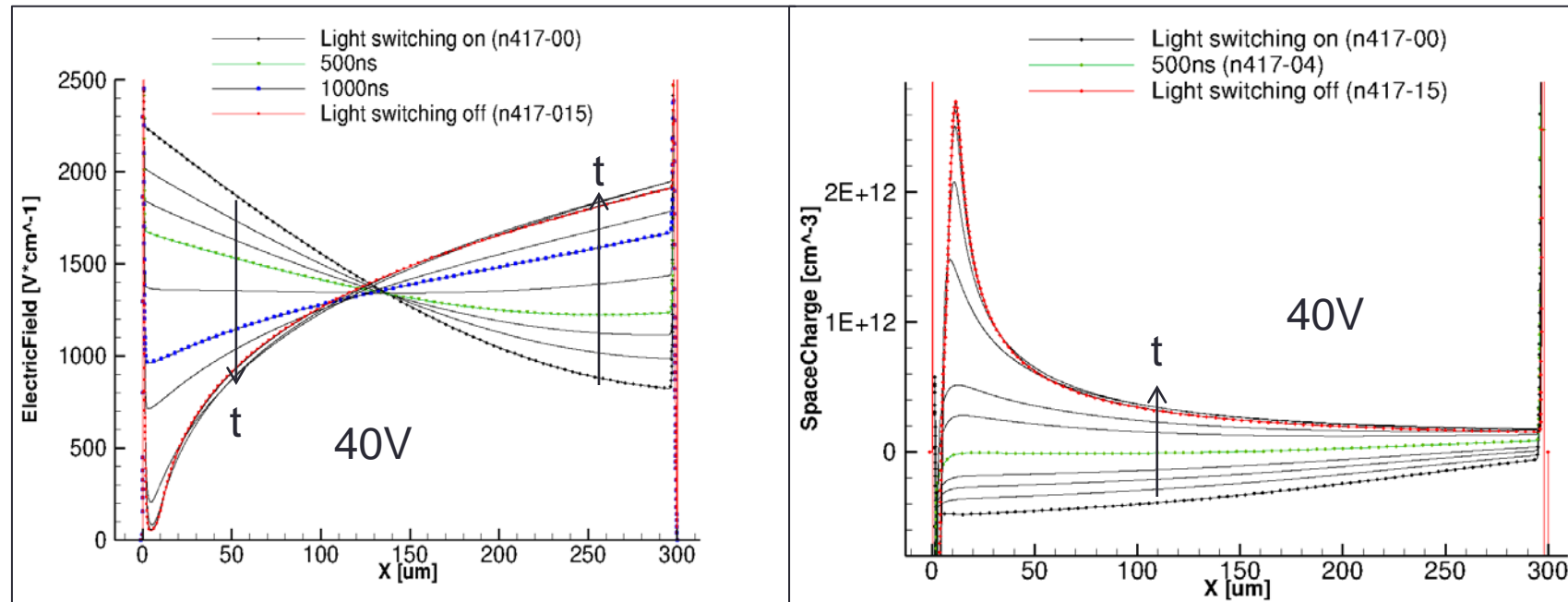
Current drop for high fluence and low voltage (Voltage scan)



Observation:

- Decrease in current for $\leq 50V$ for highest fluence $\Phi= 1e15$ p/cm²
- This is a result of a reduction of the active volume due to the opposing field from occupied defects
- The leakage current drops and gives a negative contribution to transient photocurrent

Time evolution of E-field and space charge density



➤ For voltages below 60V the detector goes into underdepletion at the front junction during the pulse which leads to a reduction in photocurrent

➤ Figure shows space charge sign inversion (from neg. to pos. space charge)

Measurements and Method

Signal Components

- For irradiated detectors we expect the current AFTER illumination to be of the form:

$$I(t) = \sum_i A_i \exp(-t / \tau_i)$$

- In the case of two time-constants:

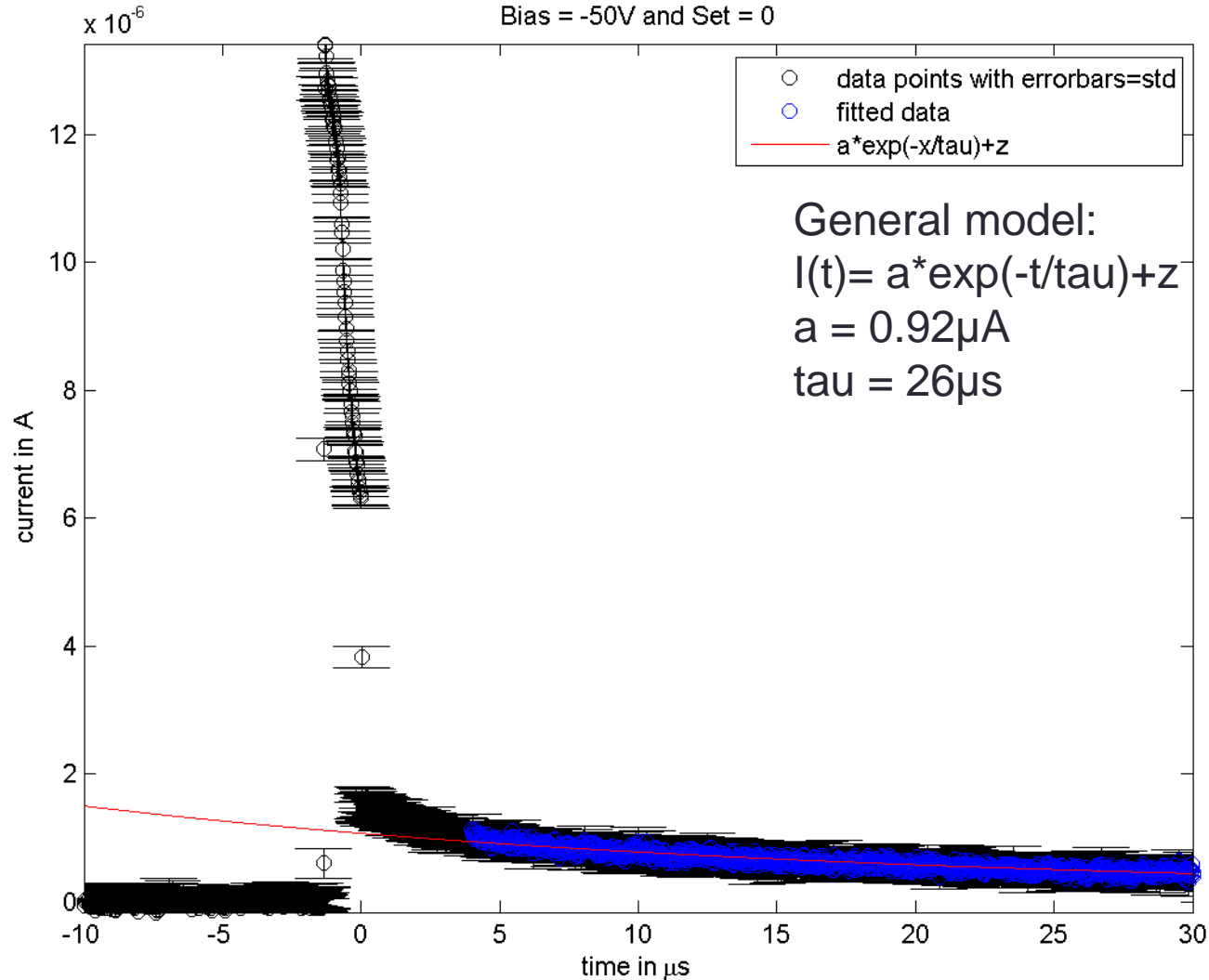
$$I(t) = A_1 \exp(-t / \tau_1) + A_2 \exp(-t / \tau_2)$$

with free parameters A_1 , A_2 , τ_1 and τ_2 .

Tau extraction for “slow” transient: τ_2

FZ_2328-11_A_Set1613: Fitting τ_2 for pulse length = $1.5\mu\text{s}$

Bias = -50V and Set = 0



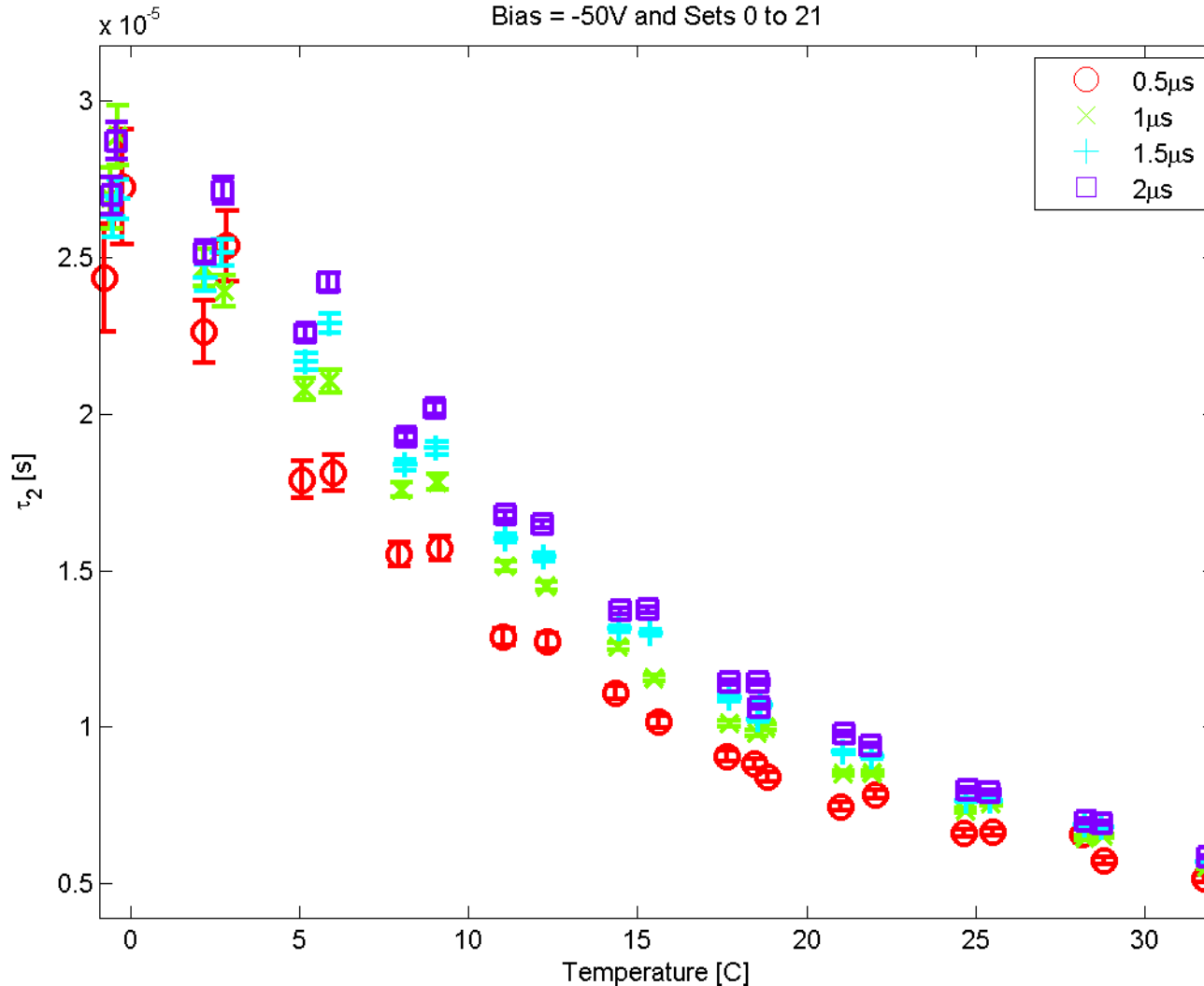
$\Phi=5e14 \text{ p/cm}^2$

Fitting process:

- Averaged data with errorbars = std of 10 “identical” measurements
- Only fitting to “tail” of transient: τ_2
- 95% confidence interval also obtained

Tau extraction for “slow” transient: τ_2

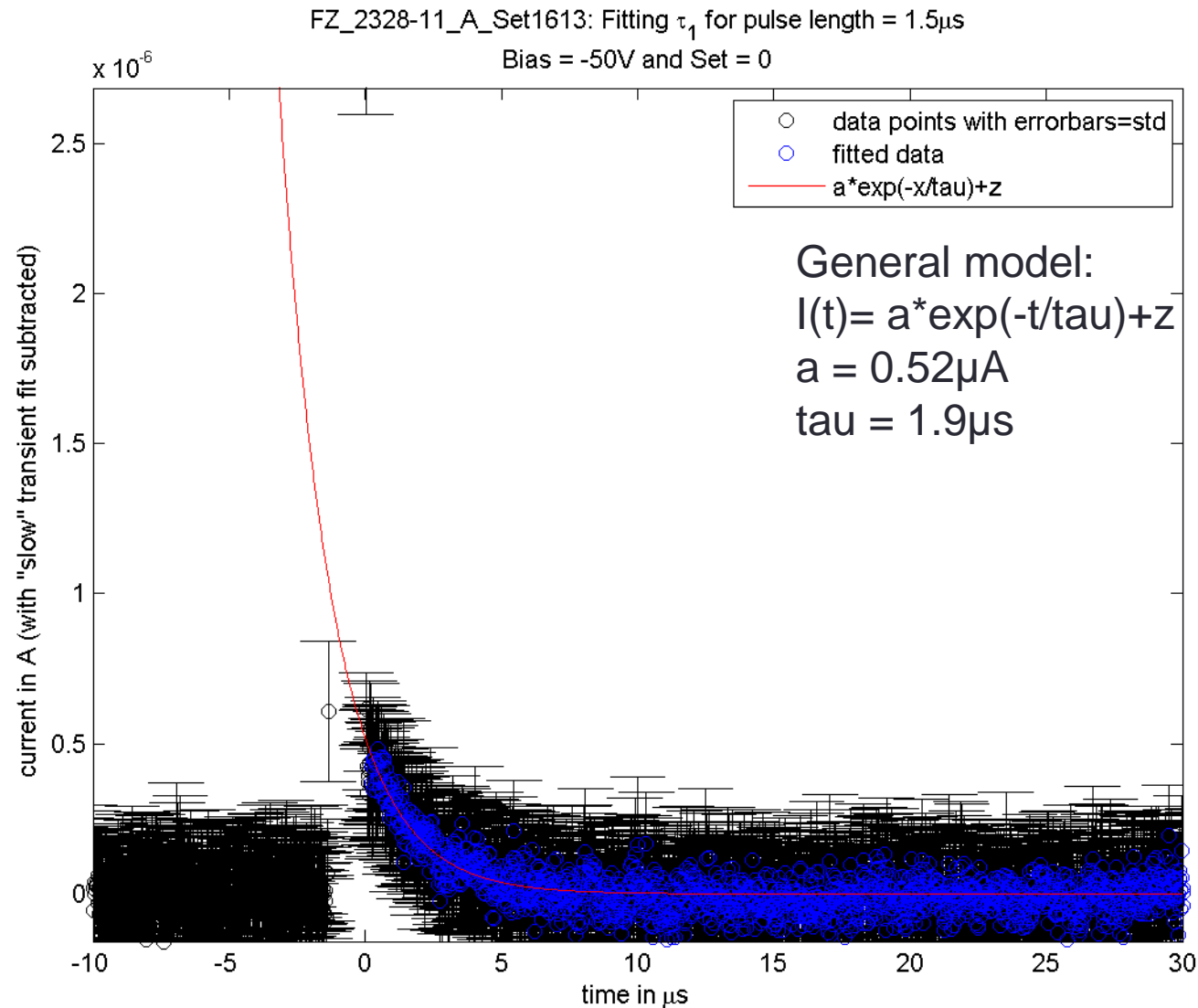
FZ_2328-11_A_Set1613: Fitted τ_2 vs temperature
Bias = -50V and Sets 0 to 21



$\Phi=5e14$ p/cm²

- Each temperature was measured twice (0 to 30°C and down to 0°C)
- Data shows correct trend and is reproducible
- Tau extraction seems to work for “slow” transient

Tau extraction for “fast” transient: τ_1



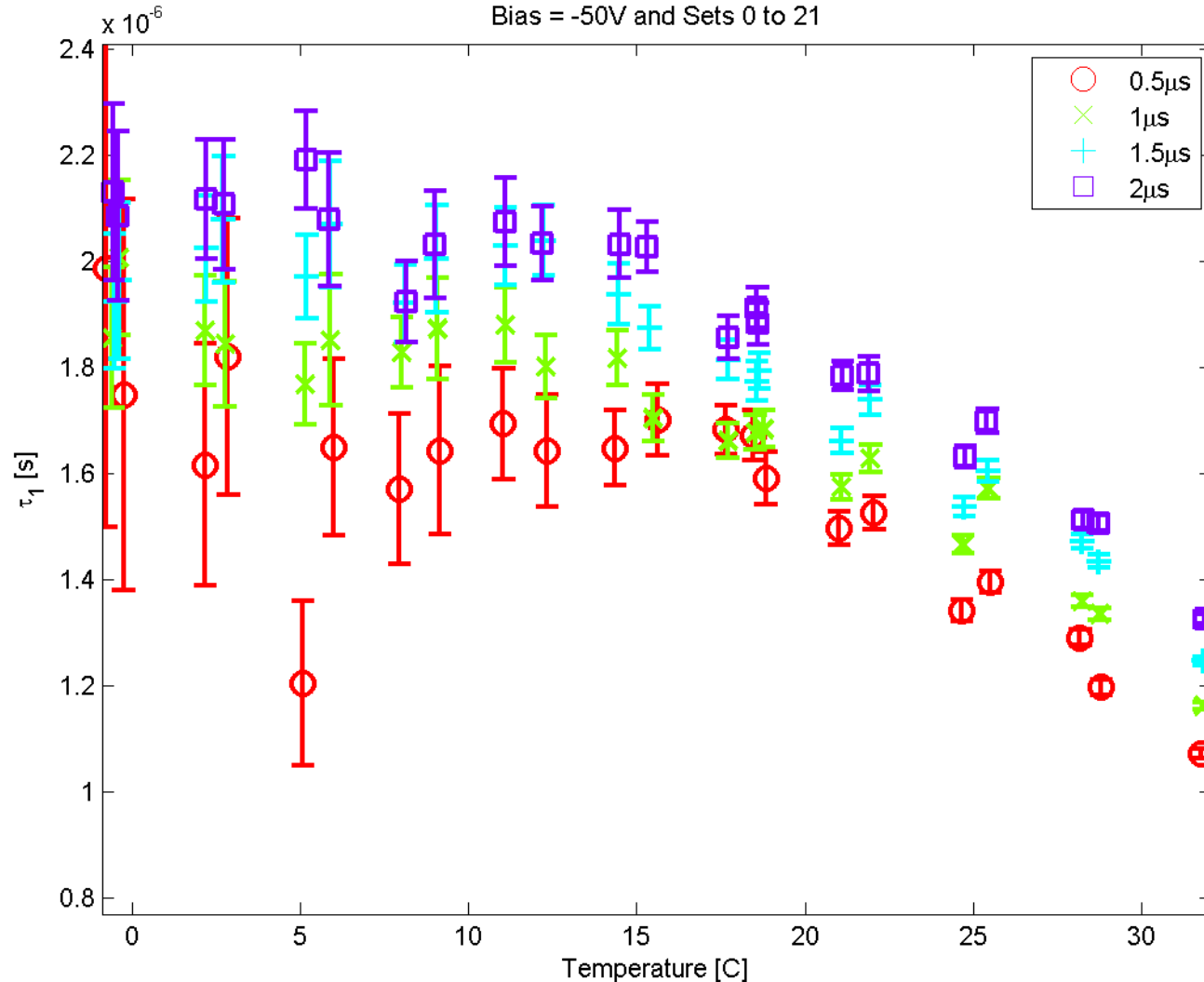
$$\Phi = 5e14 \text{ p/cm}^2$$

Fitting process:

- “Slow” transient subtracted before fitting to averaged data with errorbars = std of 10 “identical” measurements
- Nearly all points after illumination are taken

Tau extraction for “fast” transient: τ_1

FZ_2328-11_A_Set1613: Fitted τ_1 vs temperature
Bias = -50V and Sets 0 to 21



$\Phi=5e14$ p/cm²

- Each temperature was measured twice (0 to 30°C and down to 0°C)
- Data shows big spread for low temperature
- Tau extraction seems to fail for “fast” transient

Parameter extraction: τ -fitting & Arrhenius plot

- The detrapping time constant is linked to defect parameters by:

$$\tau_h = \frac{1}{\sigma_h v_h N_V} \exp\left(\frac{E_t}{k_B T}\right)$$

absolute value of the energy level calculated from valence band maximum

σ_h ... hole detrapping cross-section
 v_h ... thermal hole velocity
 N_V ... effective density of states in valence band maximum

- Looking explicitly on T-dependence:

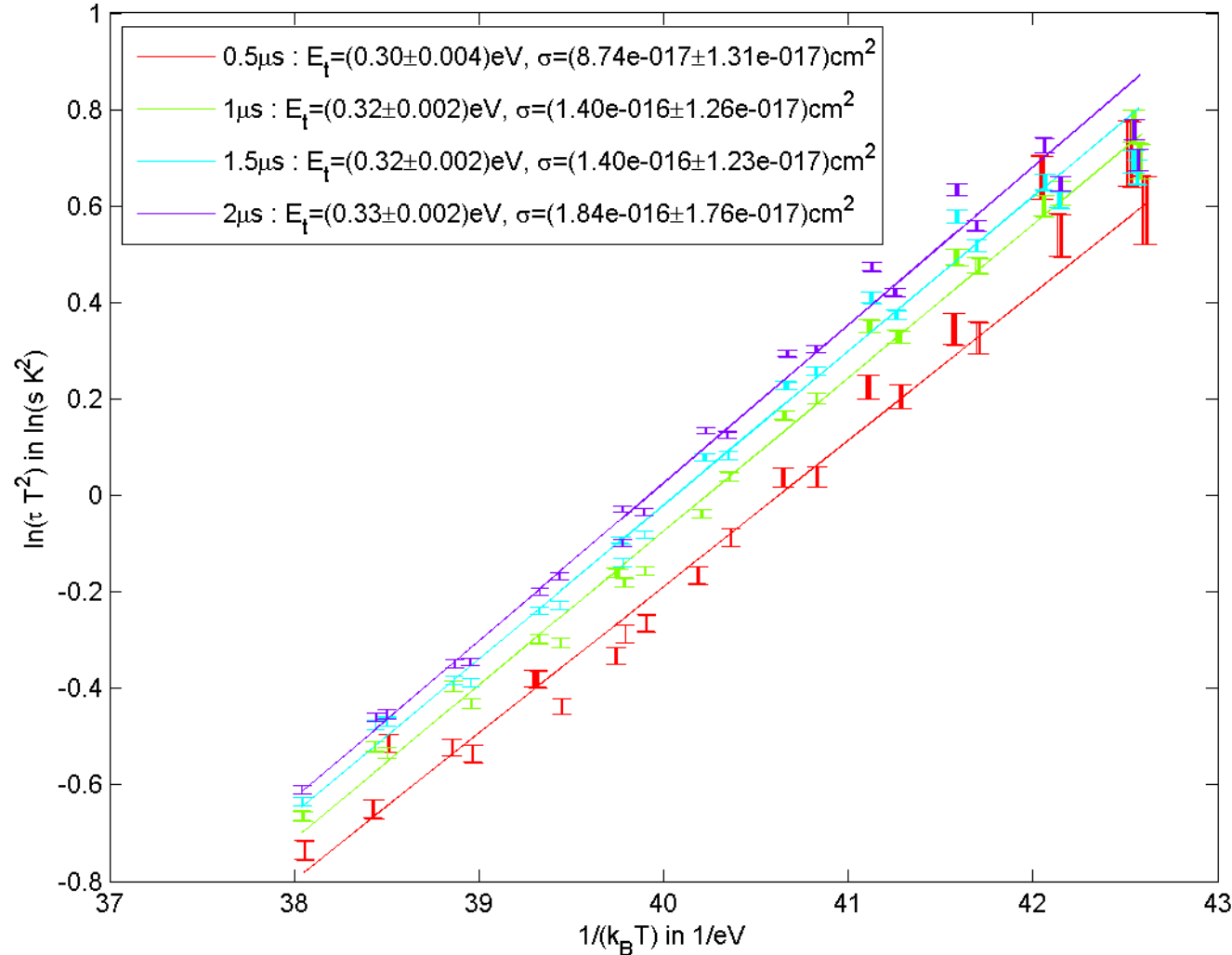
$$v_h N_V = \sqrt{\frac{3k_B T}{m_h}} \frac{1}{4} \left(\frac{2m_h k_B T}{\pi \hbar^2}\right)^{3/2} \equiv \gamma_h T^2$$

- And we can analyse data in an Arrhenius plot:

$$\ln(\tau_h T^2) = \frac{E_t}{k_B T} - \ln(\sigma_h \gamma_h) \quad \Rightarrow \quad \text{read off } E_t \text{ and } \sigma_h \text{ from slope and intersect}$$

Arrhenius plot for “slow” transient: τ_2

FZ_2328-11_A_Set1613: Fitted τ_2 values to integrated signals
Bias = -50V and Sets 0 to 21

**PRELIMINARY** $\Phi = 5 \times 10^{14} \text{ p/cm}^2$

from slope:
 $E_{\text{th}} = 0.32 \text{eV}$

from Intercept &
 $\gamma_h = 1.8 \times 10^{25} \text{ s}^{-1} (\text{mK})^{-2}$

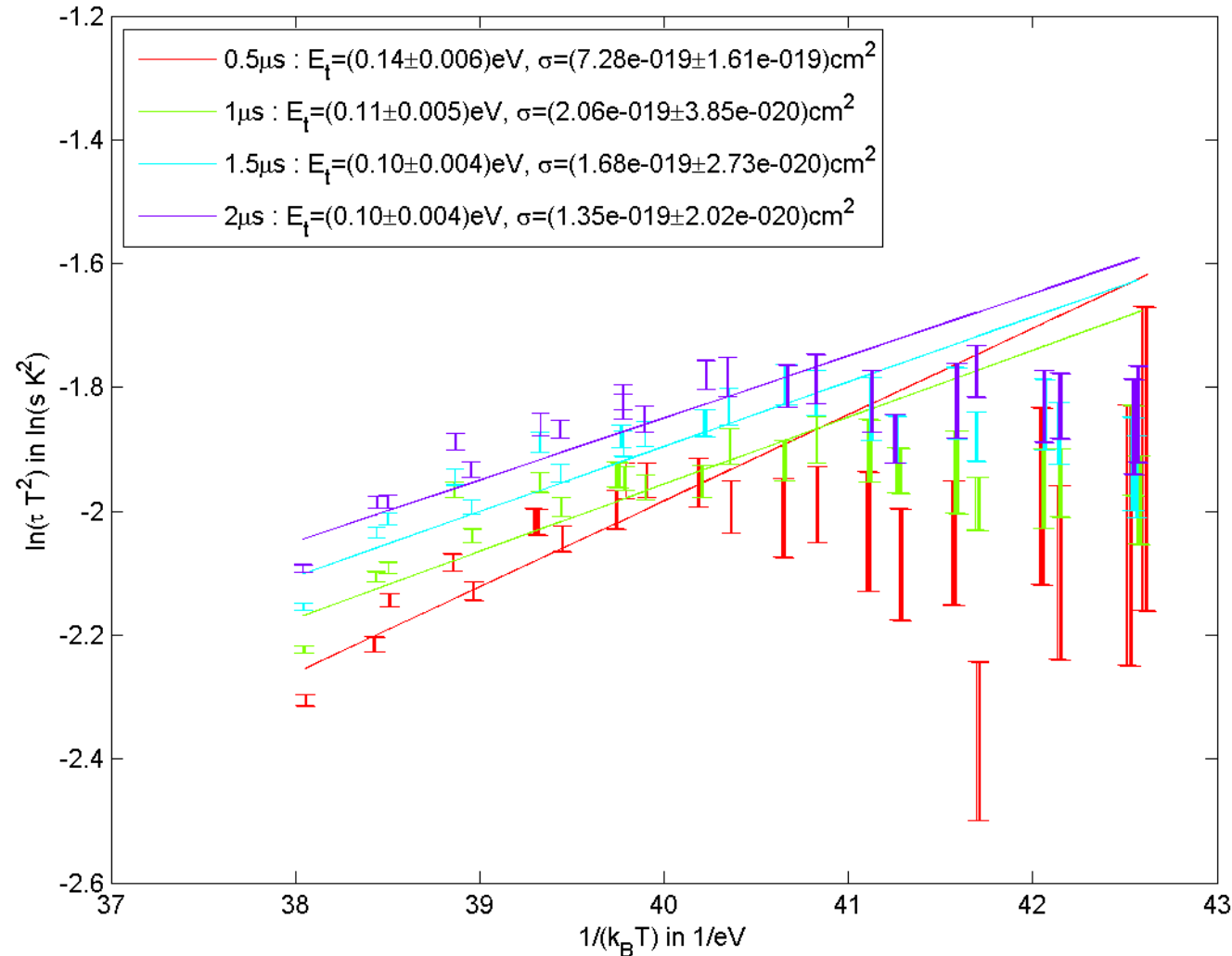
$\sigma_h = 1.4 \times 10^{-16} \text{ cm}^2$

Arrhenius plot for “fast” transient: τ_1

FZ_2328-11_A_Set1613: Fitted τ_1 values to integrated signals
Bias = -50V and Sets 0 to 21

PRELIMINARY

$\Phi = 5e14 \text{ p/cm}^2$



from fit:

$E_{th} \approx 0.1 \text{ eV}$

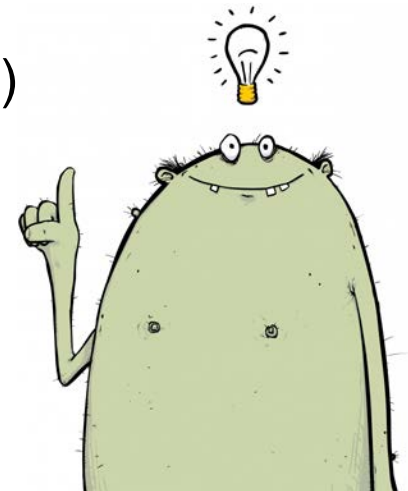
$\sigma_h \approx 1 \times 10^{-19} \text{ cm}^2$

➤ Not physically reasonable

→ maybe effect from electronics?

Conclusions

- Varying both pulse length and bias voltage together with TCAD simulations gave better understanding of the current transient formation
- But we need to ...
 - improve the extraction of the time constants τ_i from $I(t)$ or $\int I(t)dt$
(fitting to exp+exp is numerically very ill-conditioned)
 - increase the detrapping signal by choosing the “optimal” pulse length
(for given temperature and bias voltage)
 - Study behaviour with IR laser (1060nm, instead of 660nm)
which has much higher penetration depth
 - ...



Thanks for your attention!